



**THE DATASHEET OF  
74HCT4094N,112**



# 74HC4094; 74HCT4094

## 8-stage shift-and-store bus register

Rev. 6 — 31 December 2012

Product data sheet

### 1. General description

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The 74HC4094; 74HCT4094 is an 8-bit serial-in/serial or parallel-out shift register with a storage register and 3-state outputs. Both the shift and storage register have separate clocks. The device features a serial input (D) and two serial outputs (QS1 and QS2) to enable cascading. Data is shifted on the LOW-to-HIGH transitions of the CP input. Data is available at QS1 on the LOW-to-HIGH transitions of the CP input to allow cascading when clock edges are fast. The same data is available at QS2 on the next HIGH-to-LOW transition of the CP input to allow cascading when clock edges are slow. The data in the shift register is transferred to the storage register when the STR input is HIGH. Data in the storage register appears at the outputs whenever the output enable input (OE) is HIGH. A LOW on OE causes the outputs to assume a high-impedance OFF-state. Operation of the OE input does not affect the state of the registers. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

### 2. Features and benefits

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- Complies with JEDEC standard JESD7A
- Input levels:
  - ◆ For 74HC4094: CMOS level
  - ◆ For 74HCT4094: TTL level
- Low-power dissipation
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2 000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

### 3. Applications

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- Serial-to-parallel data conversion
- Remote control holding register



## 4. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74HC4094N	-40 °C to +125 °C	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
74HCT4094N				
74HC4094D	-40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HCT4094D				
74HC4094DB	-40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HCT4094DB				
74HC4094PW	-40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1

## 5. Functional diagram

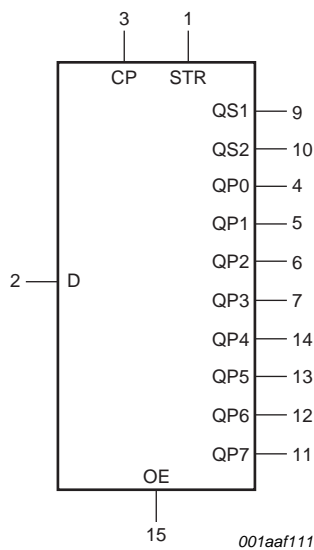


Fig 1. Functional diagram

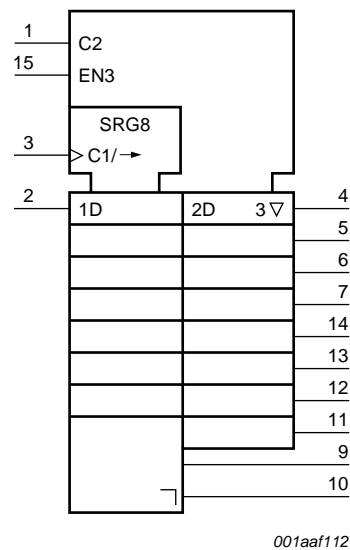


Fig 2. Logic symbol

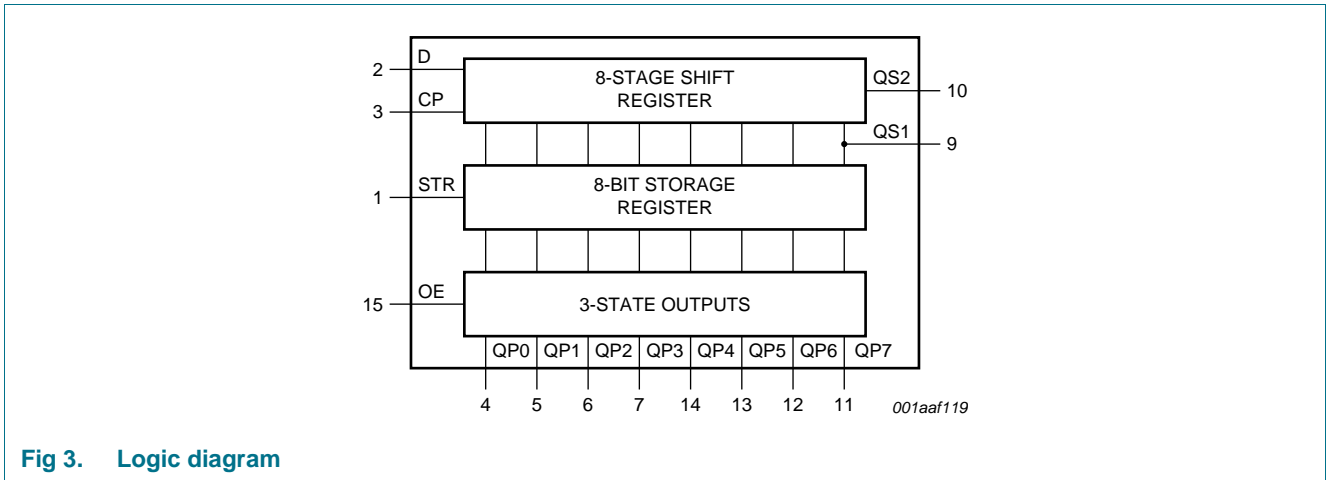


Fig 3. Logic diagram

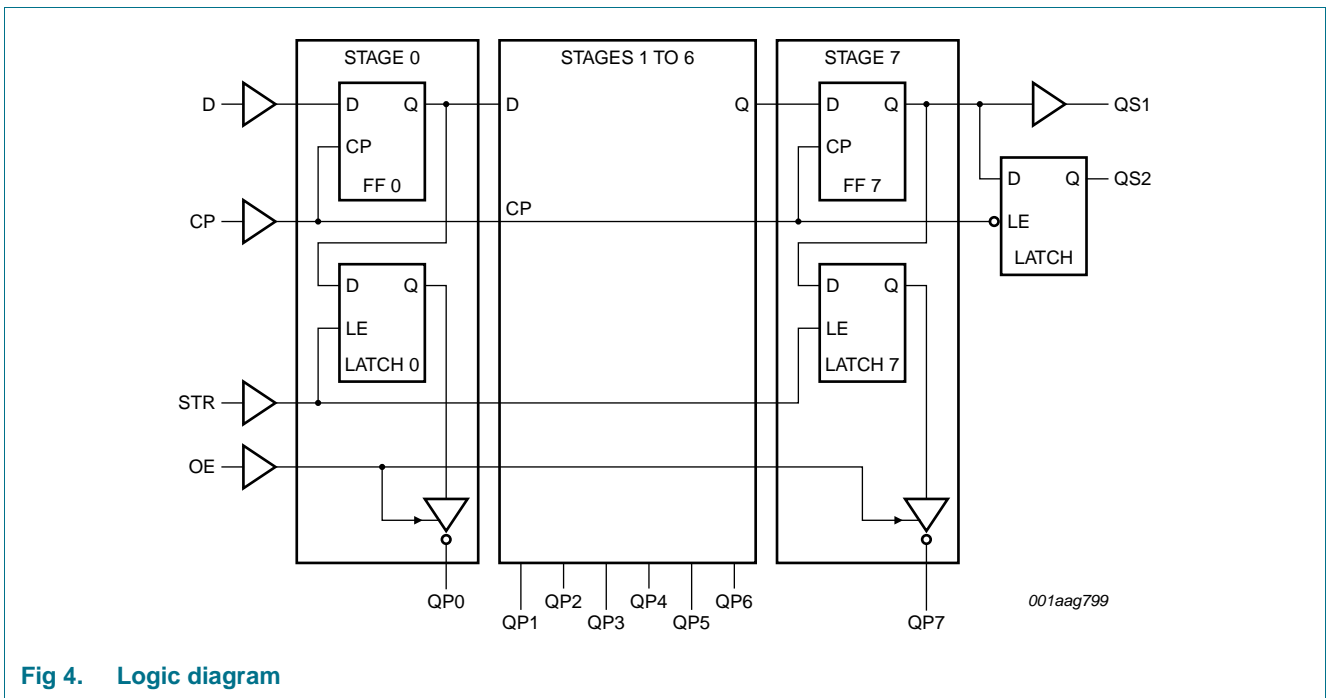


Fig 4. Logic diagram

## 6. Pinning information

### 6.1 Pinning

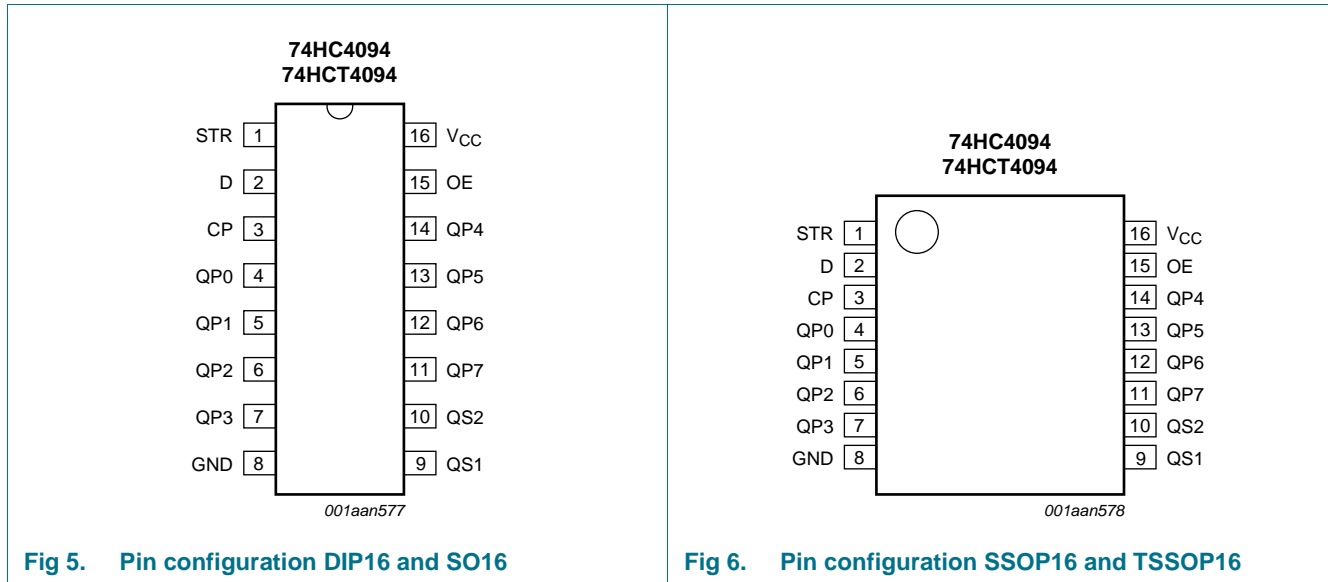


Fig 5. Pin configuration DIP16 and SO16

Fig 6. Pin configuration SSOP16 and TSSOP16

### 6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
STR	1	strobe input
D	2	data input
CP	3	clock input
QP0 to QP7	4, 5, 6, 7, 14, 13, 12, 11	parallel output
V <sub>SS</sub>	8	ground supply voltage
QS1, QS2	9, 10	serial output
OE	15	output enable input
V <sub>DD</sub>	16	supply voltage

## 7. Functional description

Table 3. Function table<sup>[1]</sup>

Inputs				Parallel outputs		Serial outputs	
CP	OE	STR	D	QP0	QPn	QS1	QS2
↑	L	X	X	Z	Z	Q6S	NC
↓	L	X	X	Z	Z	NC	Q7S
↑	H	L	X	NC	NC	Q6S	NC
↑	H	H	L	L	QPn - 1	Q6S	NC
↑	H	H	H	H	QPn - 1	Q6S	NC
↓	H	H	H	NC	NC	NC	Q7S

- [1] At the positive clock edge, the information in the 7th register stage is transferred to the 8th register stage and the QSn outputs.  
 H = HIGH voltage level; L = LOW voltage level; X = don't care;  
 ↑ = positive-going transition; ↓ = negative-going transition;  
 Z = HIGH-impedance OFF-state; NC = no change;  
 Q6S = the data in register stage 6 before the LOW to HIGH clock transition;  
 Q7S = the data in register stage 7 before the HIGH to LOW clock transition.

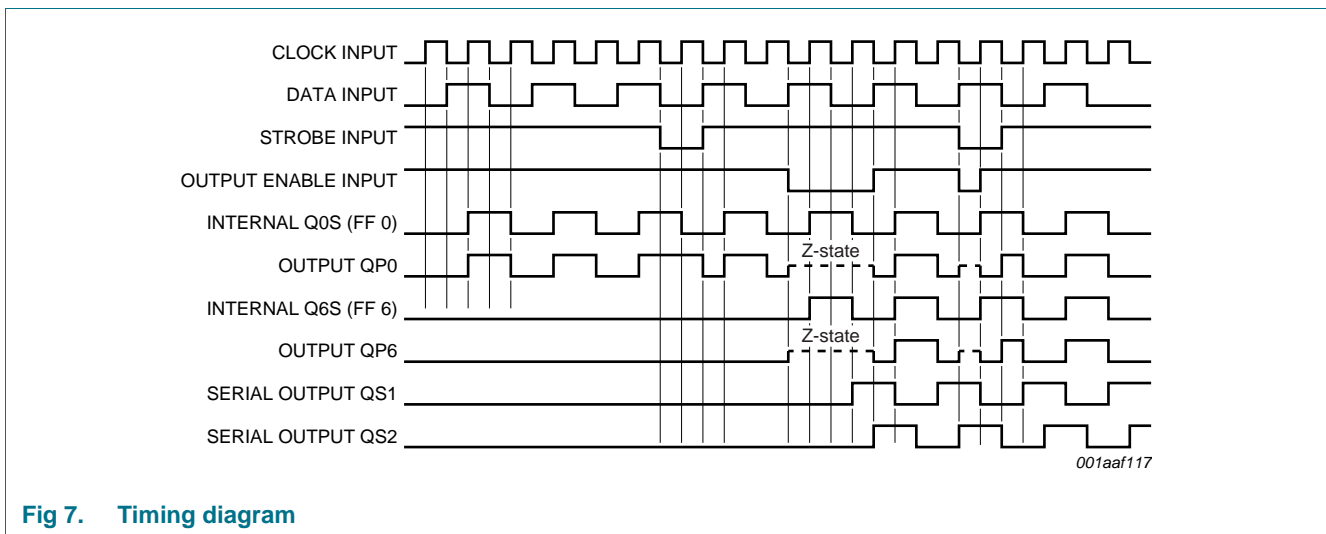


Fig 7. Timing diagram

## 8. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit	
$V_{CC}$	supply voltage		-0.5	+7	V	
$I_{IK}$	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$	-	$\pm 20$	mA	
$I_{OK}$	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$	-	$\pm 20$	mA	
$I_O$	output current	$V_O = -0.5\text{ V}$ to $(V_{CC} + 0.5\text{ V})$	-	$\pm 25$	mA	
$I_{CC}$	supply current		-	+50	mA	
$I_{GND}$	ground current		-	-50	mA	
$T_{stg}$	storage temperature		-65	+150	°C	
$P_{tot}$	total power dissipation	DIP16 package	[1]	-	750	mW
		SO16, SSOP16 and TSSOP16 packages	[2]	-	500	mW

[1] For DIP16 package:  $P_{tot}$  derates linearly with 12 mW/K above 70 °C.

[2] For SO16:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.

For SSOP16 and TSSOP16 packages:  $P_{tot}$  derates linearly with 5.5 mW/K above 60 °C.

## 9. Recommended operating conditions

**Table 5. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC4094			74HCT4094			Unit
			Min	Typ	Max	Min	Typ	Max	
$V_{CC}$	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
$V_I$	input voltage		0	-	$V_{CC}$	0	-	$V_{CC}$	V
$V_O$	output voltage		0	-	$V_{CC}$	0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.0\text{ V}$	-	-	625	-	-	-	ns/V
		$V_{CC} = 4.5\text{ V}$	-	1.67	139	-	1.67	139	ns/V
		$V_{CC} = 6.0\text{ V}$	-	-	83	-	-	-	ns/V

## 10. Static characteristics

**Table 6. Static characteristics**
*At recommended operating conditions; voltages are referenced to GND (ground = 0 V).*

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC4094</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.5	-	±5.0	-	±10.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	8.0	-	80	-	160	μA
C <sub>I</sub>	input capacitance		-	3.5	-					pF
<b>74HCT4094</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -20 μA	4.4	4.5	-	4.4	-	4.4	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 20 μA	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA	-	0.15	0.26	-	0.33	-	0.4	V

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$I_I$	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 5.5$ V	-	-	±0.1	-	±1.0	-	±1.0	µA
$I_{OZ}$	OFF-state output current	$V_I = V_{IH}$ or $V_{IL}$ ; $V_{CC} = 5.5$ V; $V_O = V_{CC}$ or GND per input pin; other inputs at $V_{CC}$ or GND; $I_O = 0$ A	-	-	±0.5	-	±5.0	-	±10	µA
$I_{CC}$	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5$ V	-	-	8.0	-	80	-	160	µA
$\Delta I_{CC}$	additional supply current	$V_I = V_{CC} - 2.1$ V; other inputs at $V_{CC}$ or GND; $V_{CC} = 4.5$ V to 5.5 V; $I_O = 0$ A	-	-	-	-	-	-	-	-
		per input pin; STR input	-	100	360	-	450	-	490	µA
		per input pin; OE input	-	150	540	-	675	-	735	µA
		per input pin; CP input	-	150	540	-	675	-	735	µA
		per input pin; D input	-	40	144	-	180	-	196	µA
$C_I$	input capacitance		-	3.5	-					pF

## 11. Dynamic characteristics

**Table 7. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V);  $C_L = 50$  pF unless otherwise specified; for test circuit see [Figure 12](#).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC4094</b>										
$t_{pd}$	propagation delay	CP to QS1; see <a href="#">Figure 8</a> <sup>[1]</sup>								
		$V_{CC} = 2.0$ V	-	50	150	-	190	-	225	ns
		$V_{CC} = 4.5$ V	-	18	30	-	38	-	45	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	15	-	-	-	-	-	ns
		$V_{CC} = 6.0$ V	-	14	26	-	33	-	38	ns
		CP to QS2; see <a href="#">Figure 8</a> <sup>[1]</sup>								
		$V_{CC} = 2.0$ V	-	44	135	-	170	-	205	ns
		$V_{CC} = 4.5$ V	-	16	27	-	34	-	41	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	13	-	-	-	-	-	ns
		$V_{CC} = 6.0$ V	-	13	23	-	29	-	35	ns
		CP to QPn; see <a href="#">Figure 8</a> <sup>[1]</sup>								
		$V_{CC} = 2.0$ V	-	63	195	-	245	-	295	ns
		$V_{CC} = 4.5$ V	-	23	39	-	49	-	59	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	20	-	-	-	-	-	ns
		$V_{CC} = 6.0$ V	-	18	33	-	42	-	50	ns
		STR to QPn; see <a href="#">Figure 9</a> <sup>[1]</sup>								
$V_{CC} = 2.0$ V	-	58	180	-	225	-	270	ns		
$V_{CC} = 4.5$ V	-	21	36	-	45	-	54	ns		
$V_{CC} = 5$ V; $C_L = 15$ pF	-	18	-	-	-	-	-	ns		
$V_{CC} = 6.0$ V	-	17	31	-	38	-	46	ns		
$t_{en}$	enable time	OE to QPn; see <a href="#">Figure 11</a> <sup>[2]</sup>								
		$V_{CC} = 2.0$ V	-	55	175	-	220	-	265	ns
		$V_{CC} = 4.5$ V	-	20	35	-	44	-	53	ns
		$V_{CC} = 6.0$ V	-	16	30	-	37	-	45	ns
$t_{dis}$	disable time	OE to QPn; see <a href="#">Figure 11</a> <sup>[3]</sup>								
		$V_{CC} = 2.0$ V	-	41	125	-	155	-	190	ns
		$V_{CC} = 4.5$ V	-	15	25	-	31	-	38	ns
		$V_{CC} = 6.0$ V	-	12	21	-	26	-	32	ns
$t_t$	transition time	QPn and QSn; see <a href="#">Figure 8</a> <sup>[4]</sup>								
		$V_{CC} = 2.0$ V	-	19	75	-	95	-	110	ns
		$V_{CC} = 4.5$ V	-	7	15	-	19	-	22	ns
		$V_{CC} = 6.0$ V	-	6	13	-	16	-	19	ns

**Table 7. Dynamic characteristics ...continued**

Voltages are referenced to GND (ground = 0 V);  $C_L = 50$  pF unless otherwise specified; for test circuit see [Figure 12](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$t_W$	pulse width	CP HIGH or LOW; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0$ V	80	14	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V	16	5	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	4	-	17	-	20	-	ns
		STR HIGH; see <a href="#">Figure 9</a>								
		$V_{CC} = 2.0$ V	80	14	-	100	-	120	-	ns
$t_{SU}$	set-up time	D to CP; see <a href="#">Figure 10</a>								
		$V_{CC} = 2.0$ V	50	14	-	65	-	75	-	ns
		$V_{CC} = 4.5$ V	10	5	-	13	-	15	-	ns
		$V_{CC} = 6.0$ V	9	4	-	11	-	13	-	ns
		CP to STR; see <a href="#">Figure 9</a>								
		$V_{CC} = 2.0$ V	100	28	-	125	-	150	-	ns
$t_H$	hold time	D to CP; see <a href="#">Figure 10</a>								
		$V_{CC} = 2.0$ V	3	-6	-	3	-	3	-	ns
		$V_{CC} = 4.5$ V	3	-2	-	3	-	3	-	ns
		$V_{CC} = 6.0$ V	3	-2	-	3	-	3	-	ns
		CP to STR; see <a href="#">Figure 9</a>								
		$V_{CC} = 2.0$ V	0	-14	-	0	-	0	-	ns
$f_{max}$	maximum frequency	CP; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0$ V	6.0	28	-	4.8	-	4.0	-	MHz
		$V_{CC} = 4.5$ V	30	87	-	24	-	20	-	MHz
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	95	-	-	-	-	-	MHz
$C_{PD}$	power dissipation capacitance	$V_{CC} = 6.0$ V	35	103	-	28	-	24	-	MHz
		$C_L = 50$ pF; $f = 1$ MHz; $V_I = GND$ to $V_{CC}$	5	-	83	-	-	-	-	pF

**Table 7. Dynamic characteristics ...continued**

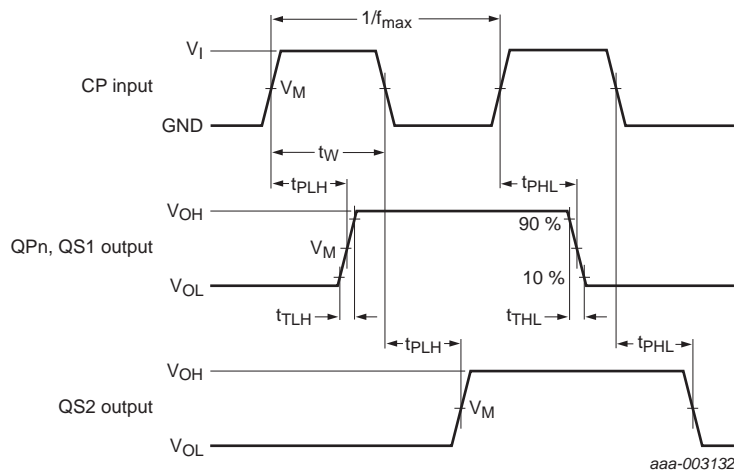
Voltages are referenced to GND (ground = 0 V);  $C_L = 50$  pF unless otherwise specified; for test circuit see [Figure 12](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HCT4094</b>										
$t_{pd}$	propagation delay	CP to QS1; see <a href="#">Figure 8</a> [1]								
		$V_{CC} = 4.5$ V	-	23	39	-	49	-	59	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	19	-	-	-	-	-	ns
		CP to QS2; see <a href="#">Figure 8</a> [1]								
		$V_{CC} = 4.5$ V	-	21	36	-	45	-	54	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	18	-	-	-	-	-	ns
		CP to QPn; see <a href="#">Figure 8</a> [1]								
		$V_{CC} = 4.5$ V	-	25	43	-	54	-	65	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	21	-	-	-	-	-	ns
$t_{en}$	enable time	STR to QPn; see <a href="#">Figure 9</a> [1]								
		$V_{CC} = 4.5$ V	-	22	39	-	49	-	59	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	19	-	-	-	-	-	ns
$t_{dis}$	disable time	OE to QPn; see <a href="#">Figure 11</a> [2]								
		$V_{CC} = 4.5$ V	-	20	35	-	44	-	53	ns
$t_t$	transition time	OE to QPn; see <a href="#">Figure 11</a> [3]								
		$V_{CC} = 4.5$ V	-	21	35	-	44	-	53	ns
$t_t$	transition time	QPn and QSn; see <a href="#">Figure 8</a> [4]								
		$V_{CC} = 4.5$ V	-	7	15	-	19	-	22	ns
$t_W$	pulse width	CP HIGH or LOW; see <a href="#">Figure 8</a>								
		$V_{CC} = 4.5$ V	16	7	-	20	-	24	-	ns
		STR HIGH; see <a href="#">Figure 9</a>								
$t_{su}$	set-up time	$V_{CC} = 4.5$ V	16	5	-	20	-	24	-	ns
		CP to STR; see <a href="#">Figure 9</a>								
$t_{su}$	set-up time	$V_{CC} = 4.5$ V	20	9	-	25	-	30	-	ns
		Dn to CP; see <a href="#">Figure 10</a>								
		$V_{CC} = 4.5$ V	10	4	-	13	-	15	-	ns
$t_h$	hold time	CP to STR; see <a href="#">Figure 9</a>								
		$V_{CC} = 4.5$ V	0	-4	-	0	-	0	-	ns
		Dn to CP; see <a href="#">Figure 10</a>								
$t_h$	hold time	$V_{CC} = 4.5$ V	4	0	-	4	-	4	-	ns
		CP to STR; see <a href="#">Figure 9</a>								
		$V_{CC} = 4.5$ V	0	-4	-	0	-	0	-	ns
$f_{max}$	maximum frequency	CP; see <a href="#">Figure 8</a>								
		$V_{CC} = 4.5$ V	30	80	-	24	-	20	-	MHz
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	86	-	-	-	-	-	MHz
$C_{PD}$	power dissipation capacitance	$C_L = 50$ pF; $f = 1$ MHz; $V_I = GND$ to $V_{CC}$ [5]	-	92	-	-	-	-	-	pF

[1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .

- [2]  $t_{en}$  is the same as  $t_{PZH}$  and  $t_{PZL}$ .
- [3]  $t_{dis}$  is the same as  $t_{PLZ}$  and  $t_{PHZ}$ .
- [4]  $t_i$  is the same as  $t_{THL}$  and  $t_{TLH}$ .
- [5]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ ).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o)$  where:  
 $f_i$  = input frequency in MHz;  
 $f_o$  = output frequency in MHz;  
 $C_L$  = output load capacitance in pF;  
 $V_{CC}$  = supply voltage in V;  
 $N$  = number of inputs switching;  
 $\sum(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

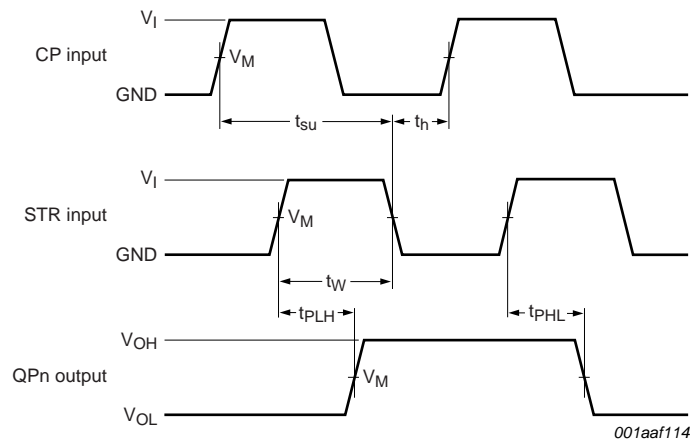
## 12. Waveforms



Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

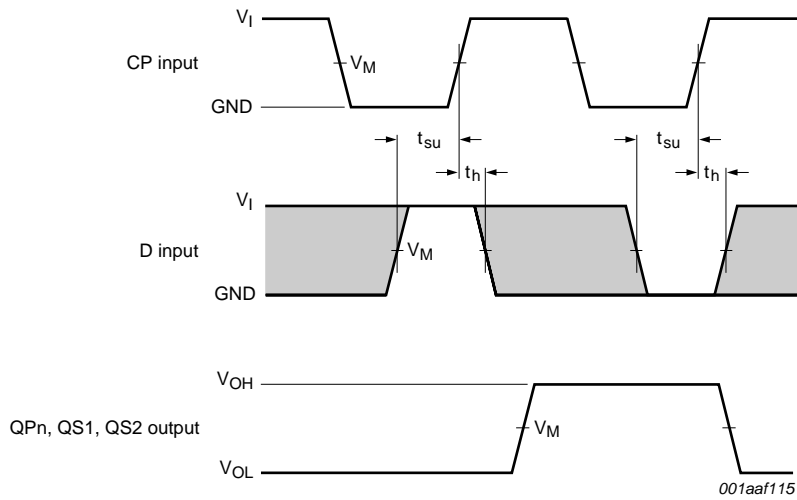
**Fig 8. Propagation delay input (CP) to output (QPn, QS1, QS2), output transition time, clock input (CP) pulse width and the maximum frequency (CP)**



Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

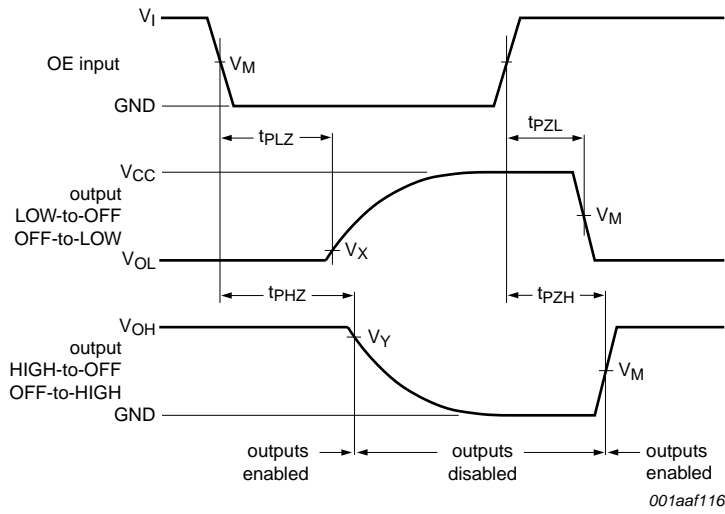
**Fig 9. Propagation delay strobe input (STR) to output (QPn), strobe input (STR) pulse width and the clock set-up and hold times for strobe input**



Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 10. The data input (D) to clock input (CP) set-up times and clock input (CP) to data input (D) hold times**

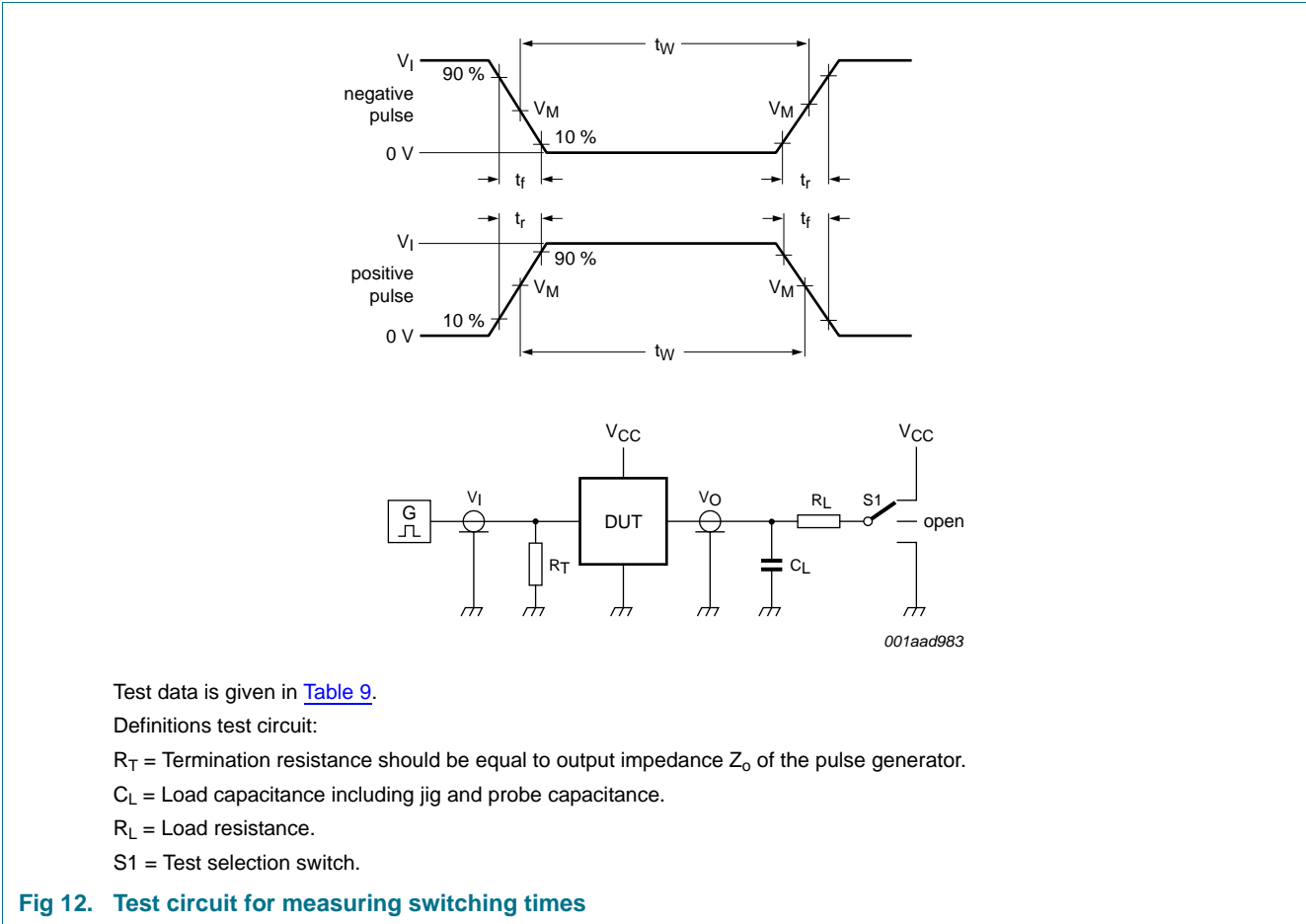


Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 11. Enable and disable times**

**Table 8. Measurement points**

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
74HC4094	$0.5V_{CC}$	$0.5V_{CC}$	$0.1V_{OH}$	$0.9V_{OH}$
74HCT4094	1.3 V	1.3 V	$0.1V_{OH}$	$0.9V_{OH}$



**Table 9. Test data**

Type	Input		Load		S1 position		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
74HC4094	$V_{CC}$	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$
74HCT4094	3 V	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$

13. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4

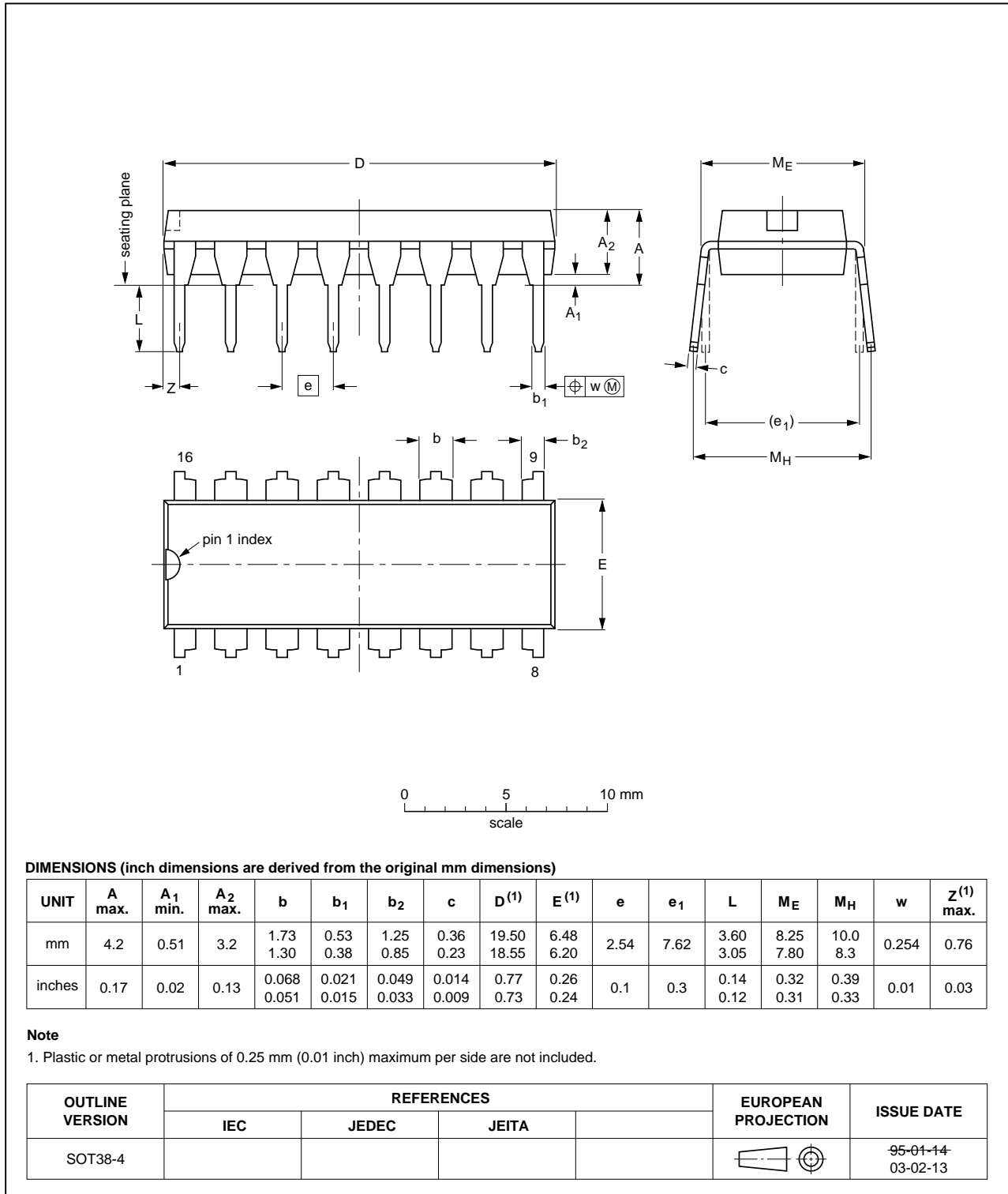


Fig 13. Package outline SOT38-4 (DIP16)

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

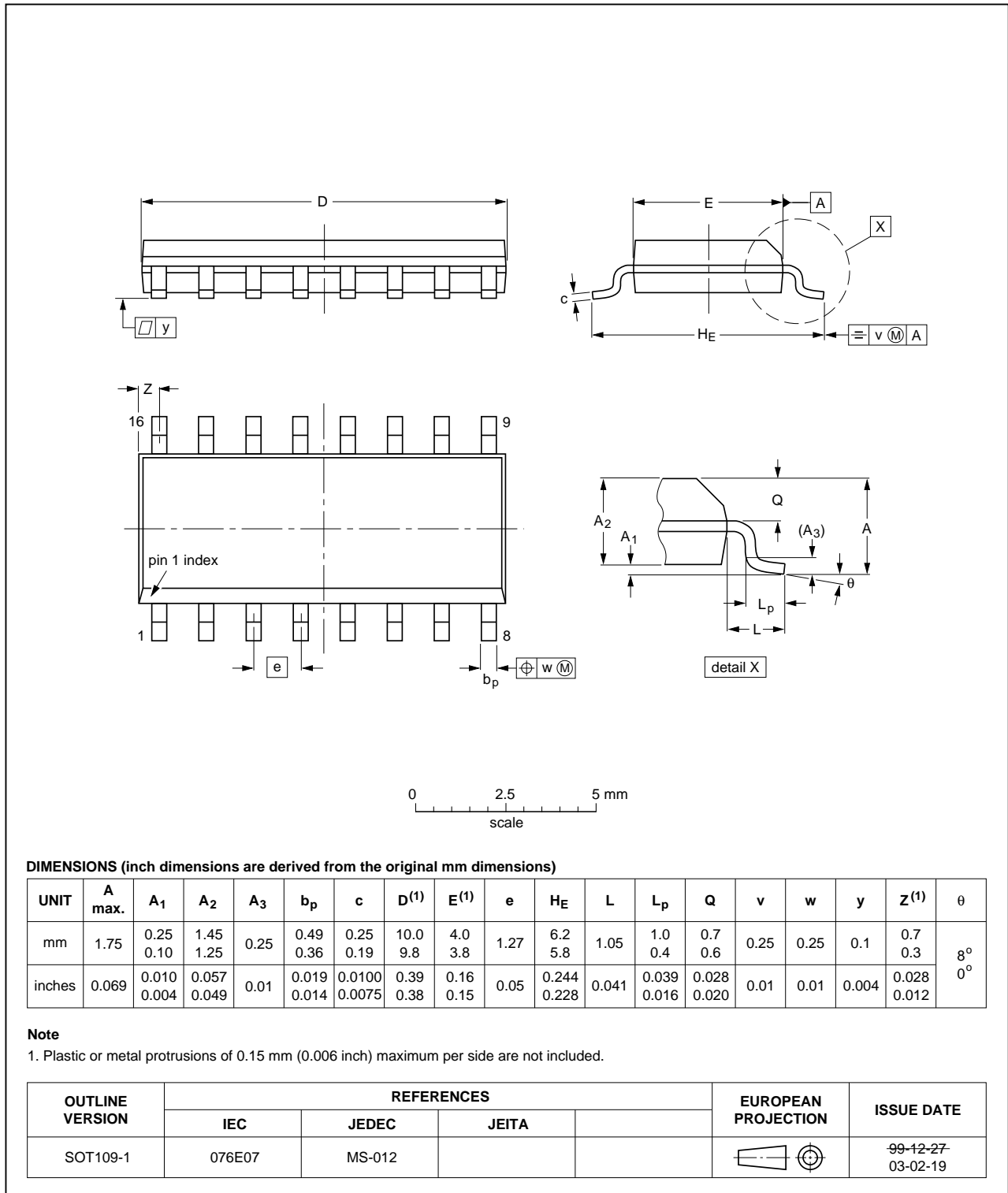


Fig 14. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

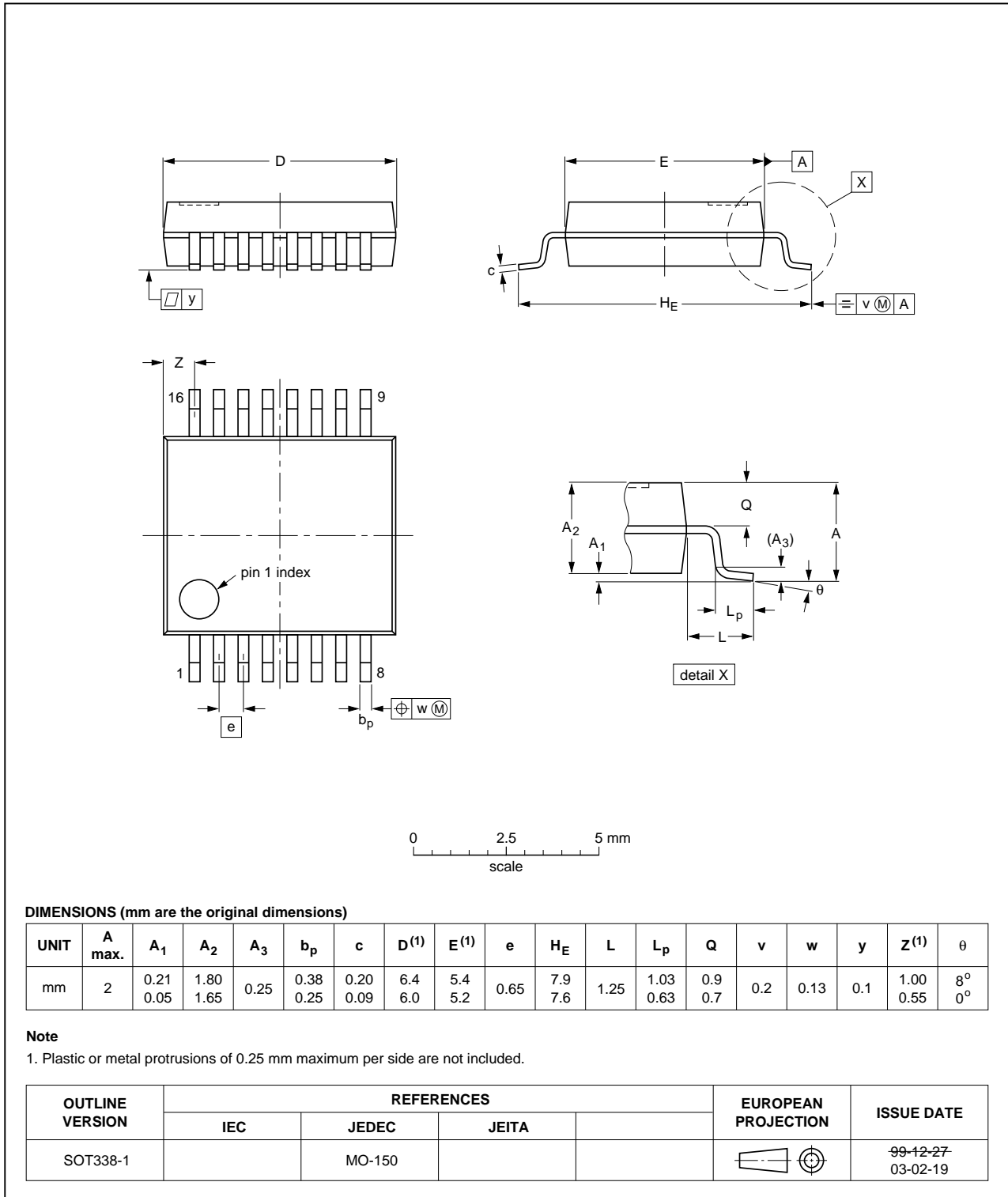


Fig 15. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

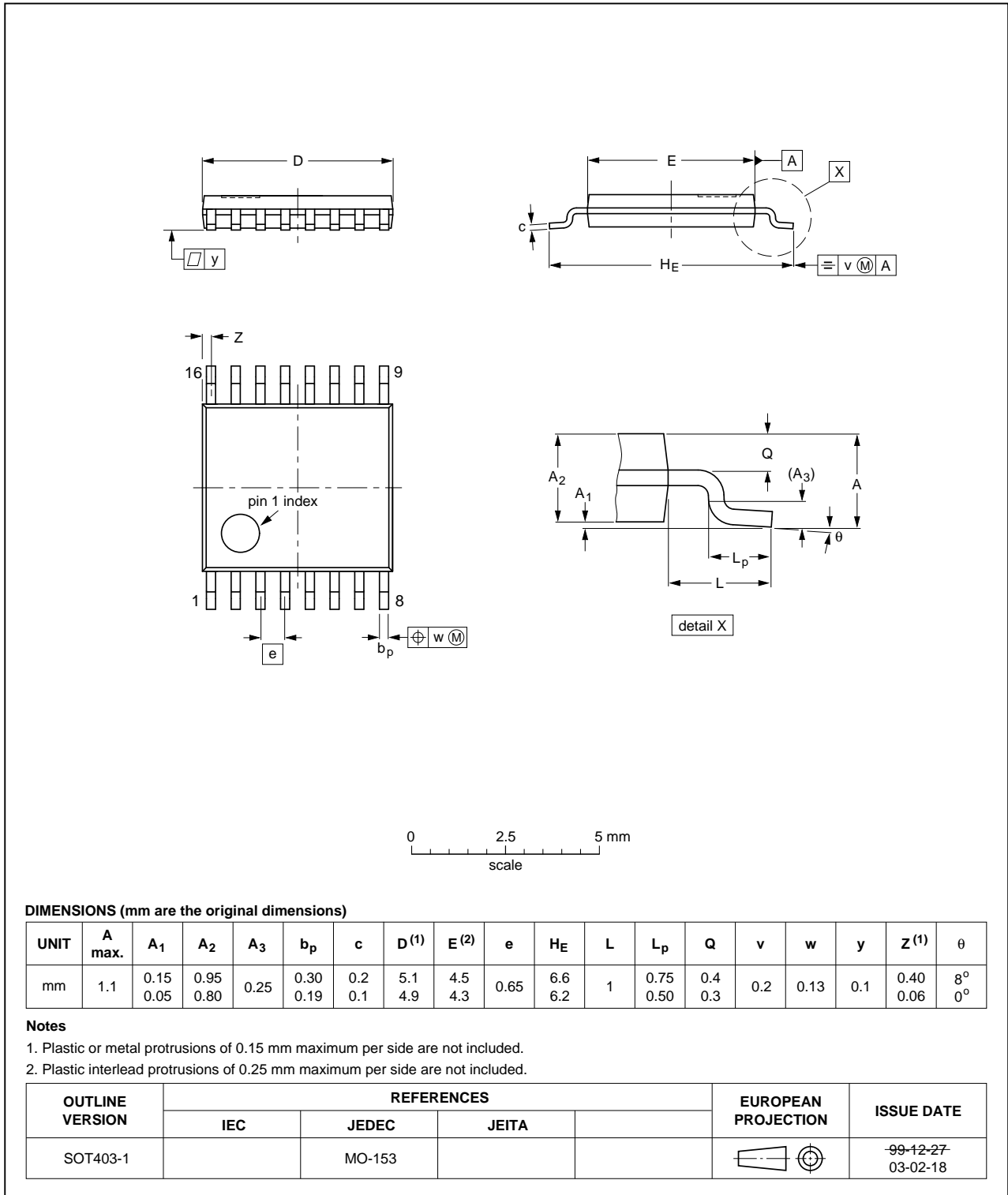


Fig 16. Package outline SOT403-1 (TSSOP16)

## 14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

## 15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT4094 v.6	20121231	Product data sheet	-	74HC_HCT4094 v.5
Modifications:	<ul style="list-style-type: none"> <li>General description updated.</li> </ul>			
74HC_HCT4094 v.5	20120628	Product data sheet	-	74HC_HCT4094 v.4
Modifications:	<ul style="list-style-type: none"> <li><math>V_X</math> and <math>V_Y</math> measurement points added to Table 8.</li> </ul>			
74HC_HCT4094 v.4	20111219	Product data sheet	-	74HC_HCT4094 v.3
Modifications:	<ul style="list-style-type: none"> <li>Legal pages updated.</li> </ul>			
74HC_HCT4094 v.3	20110214	Product data sheet	-	74HC_HCT4094_CNV v.2
74HC_HCT4094_CNV v.2	19970901	Product specification	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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## 18. Contents

<b>1</b>	<b>General description</b> .....	<b>1</b>
<b>2</b>	<b>Features and benefits</b> .....	<b>1</b>
<b>3</b>	<b>Applications</b> .....	<b>1</b>
<b>4</b>	<b>Ordering information</b> .....	<b>2</b>
<b>5</b>	<b>Functional diagram</b> .....	<b>2</b>
<b>6</b>	<b>Pinning information</b> .....	<b>4</b>
6.1	Pinning .....	4
6.2	Pin description .....	4
<b>7</b>	<b>Functional description</b> .....	<b>5</b>
<b>8</b>	<b>Limiting values</b> .....	<b>6</b>
<b>9</b>	<b>Recommended operating conditions</b> .....	<b>6</b>
<b>10</b>	<b>Static characteristics</b> .....	<b>7</b>
<b>11</b>	<b>Dynamic characteristics</b> .....	<b>9</b>
<b>12</b>	<b>Waveforms</b> .....	<b>12</b>
<b>13</b>	<b>Package outline</b> .....	<b>16</b>
<b>14</b>	<b>Abbreviations</b> .....	<b>20</b>
<b>15</b>	<b>Revision history</b> .....	<b>20</b>
<b>16</b>	<b>Legal information</b> .....	<b>21</b>
16.1	Data sheet status .....	21
16.2	Definitions .....	21
16.3	Disclaimers .....	21
16.4	Trademarks .....	22
<b>17</b>	<b>Contact information</b> .....	<b>22</b>
<b>18</b>	<b>Contents</b> .....	<b>23</b>

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Date of release: 31 December 2012

Document identifier: 74HC\_HCT4094





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